

MMQA, SZMMQA Quad Common Anode Series

SC-74 Quad Monolithic Common Anode

Transient Voltage Suppressors for ESD Protection

This quad monolithic silicon voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its quad junction common anode design protects four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Features

- SC-74 Package Allows Four Separate Unidirectional Configurations
- Peak Power – Min. 24 W @ 1.0 ms (Unidirectional), per Figure 5 Waveform
- Peak Power – Min. 150 W @ 20 μ s (Unidirectional), per Figure 6 Waveform
- Maximum Clamping Voltage @ Peak Pulse Current
- Low Leakage < 2.0 μ A
- ESD Rating of Class 3B (exceeding 16 kV) per the Human Body Model
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Packages are Available*



ON Semiconductor®

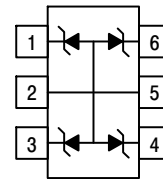
<http://onsemi.com>

**SC-74 QUAD TRANSIENT
VOLTAGE SUPPRESSOR
24 WATTS PEAK POWER
5.6 – 33 VOLTS**



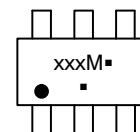
SC-74
CASE 318F
STYLE 1

PIN ASSIGNMENT



PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE

MARKING DIAGRAM



xxx = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

DEVICE MARKING & ORDERING INFORMATION

See specific marking and ordering information in the device marking and ordering information table on page 6 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MMQA, SZMMQA Quad Common Anode Series

THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Characteristic	Symbol	Value	Unit
Peak Power Dissipation @ 1.0 ms (Note 1) @ $T_A \leq 25^\circ\text{C}$	P_{pk}	24	W
Peak Power Dissipation @ 20 μs (Note 2) @ $T_A \leq 25^\circ\text{C}$	P_{pk}	150	W
Total Power Dissipation on FR-5 Board (Note 3) @ $T_A = 25^\circ\text{C}$	P_D	225 1.8	MW mW/ $^\circ\text{C}$
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Power Dissipation on Alumina Substrate (Note 4) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	MW mW/ $^\circ\text{C}$
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Second Duration)	T_L	260	$^\circ\text{C}$

1. Non-repetitive current pulse per Figure 5 and derate above $T_A = 25^\circ\text{C}$ per Figure 4.
2. Non-repetitive current pulse per Figure 6 and derate above $T_A = 25^\circ\text{C}$ per Figure 4.
3. FR-5 = 1.0 x 0.75 x 0.62 in.
4. Alumina = 0.4 x 0.3 x 0.024 in., 99.5% alumina

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

UNIDIRECTIONAL

(Circuit tied to pins 1, 2, and 5; Pins 2, 3, and 5; Pins 2, 4, and 5; or Pins 2, 5, and 6) ($V_F = 0.9\text{ V Max @ } I_F = 10\text{ mA}$)

Device (Note 8)	Breakdown Voltage				Max Reverse Leakage Current		Max Zener Impedance (Note 7)	Max Reverse Surge Current	Max Reverse Voltage @ I_{RSM} (Note 6) (Clamping Voltage)	Maximum Temperature Coefficient of V_Z	Capacitance @ 0 Volt Bias, 1 MHz	
	V _{ZT} (Note 5) (V)	@ I_{ZT}	I_R	V_R	Min	Max						
											Min	Nom
MMQA5V6T	5.32	5.6	5.88	1.0	2000	3.0	400	3.0	8.0	1.26	-	-
MMQA6V2T	5.89	6.2	6.51	1.0	700	4.0	300	2.66	9.0	10.6	-	-
MMQA6V8T	6.46	6.8	7.14	1.0	500	4.3	300	2.45	9.8	10.9	100	250
MMQA12VT	11.4	12	12.6	1.0	75	9.1	80	1.39	17.3	14	-	-
MMQA13VT	12.4	13	13.7	1.0	75	9.8	80	1.29	18.6	15	-	-
MMQA15VT	14.3	15	15.8	1.0	75	11	80	1.1	21.7	16	-	-
MMQA18VT	17.1	18	18.9	1.0	75	14	80	0.923	26	19	-	-
MMQA20VT	19	20	21	1.0	75	15	80	0.84	28.6	20.1	-	-
MMQA21VT	20	21	22.1	1.0	75	16	80	0.792	30.3	21	-	-
MMQA22VT	20.9	22	23.1	1.0	75	17	80	0.758	31.7	22	-	-
MMQA24VT	22.8	24	25.2	1.0	75	18	100	0.694	34.6	25	-	-
MMQA27VT	25.7	27	28.4	1.0	75	21	125	0.615	39	28	-	-
MMQA33VT	31.4	33	34.7	1.0	75	25	200	0.504	48.6	37	-	-

5. V_Z measured at pulse test current I_T at an ambient temperature of 25°C .
6. Surge current waveform per Figure 5 and derate per Figure 4.
7. Z_{ZT} is measured by dividing the AC voltage drop across the device by the AC current supplied. The specified limits are $I_{Z(AC)} = 0.1 I_{Z(DC)}$, with AC frequency = 1 kHz.
8. Include SZ-prefix devices where applicable.

MMQA, SZMMQA Quad Common Anode Series

TYPICAL CHARACTERISTICS

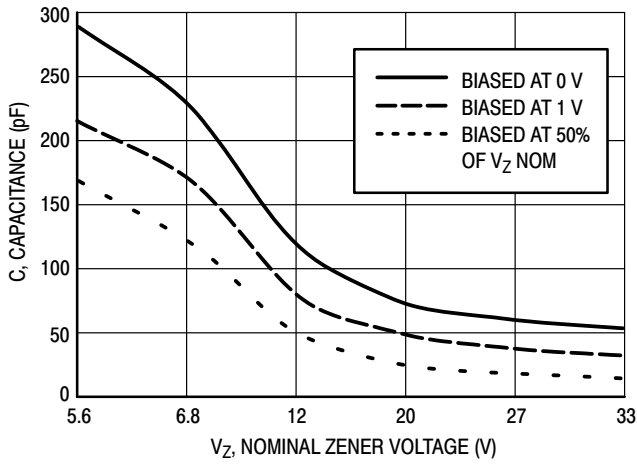


Figure 1. Typical Capacitance

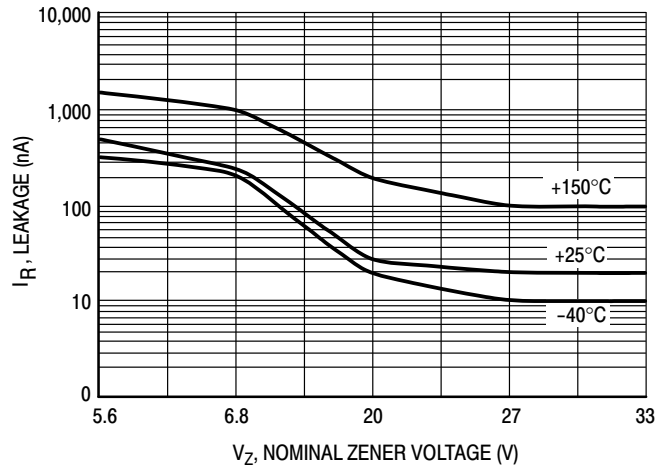


Figure 2. Typical Leakage Current

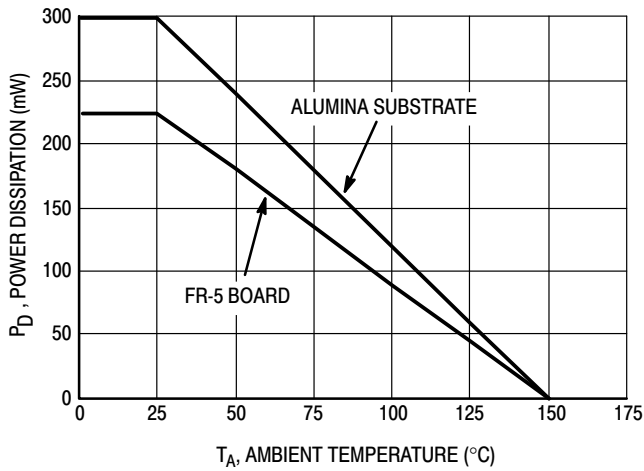


Figure 3. Steady State Power Derating Curve

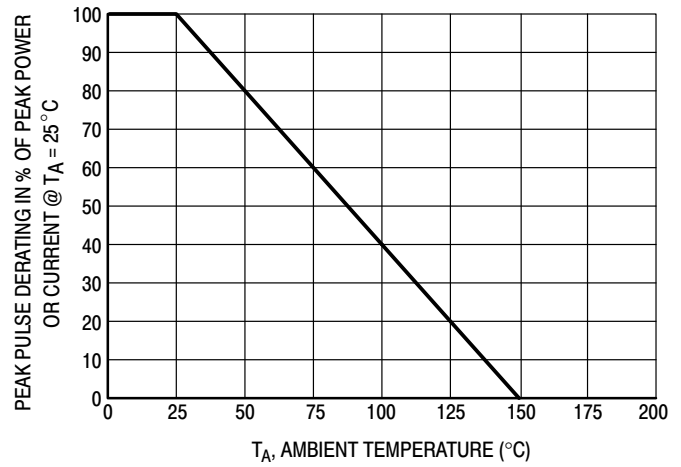


Figure 4. Pulse Derating Curve

MMQA, SZMMQA Quad Common Anode Series

TYPICAL CHARACTERISTICS

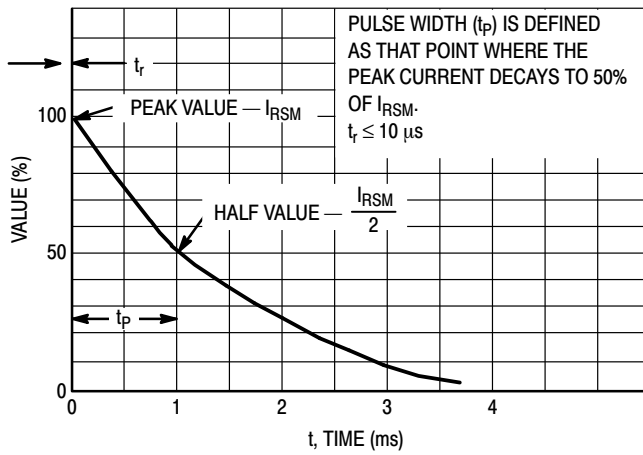


Figure 5. $10 \times 1000 \mu\text{s}$ Pulse Waveform

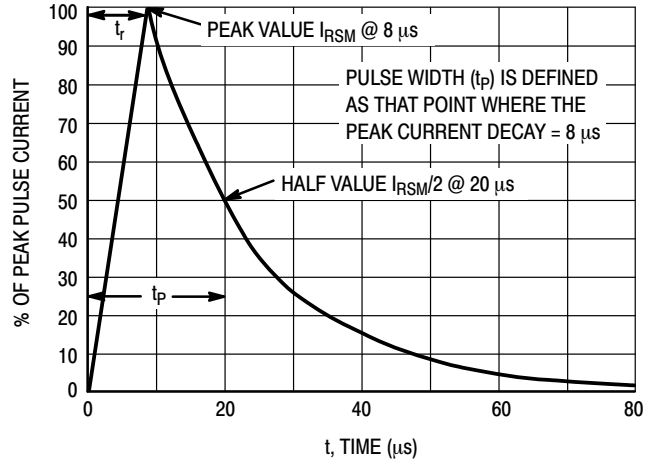


Figure 6. $8 \times 20 \mu\text{s}$ Pulse Waveform

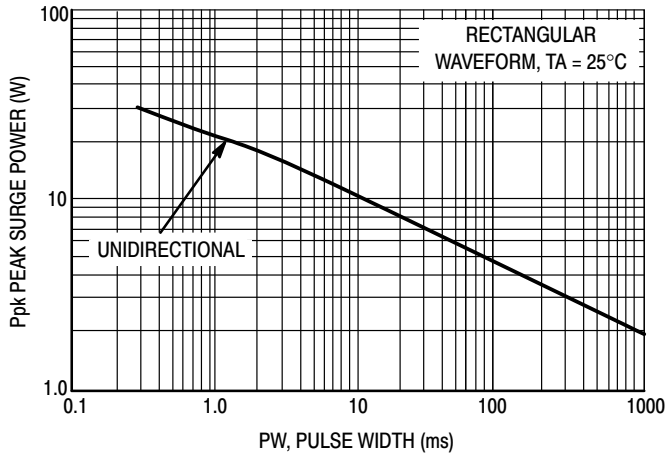


Figure 7. Maximum Non-Repetitive Surge Power, P_{pk} versus PW

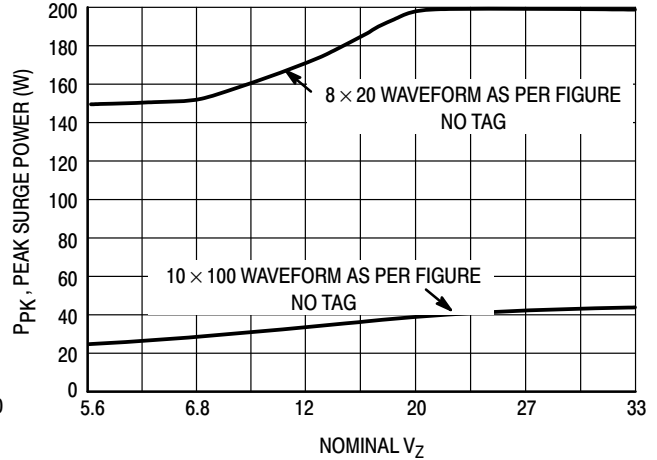


Figure 8. Typical Maximum Non-Repetitive Surge Power, P_{pk} versus V_Z

Power is defined as $V_{RSM} \times I_Z(pk)$ where V_{RSM} is the clamping voltage at $I_Z(pk)$.

MMQA, SZMMQA Quad Common Anode Series

TYPICAL COMMON ANODE APPLICATIONS

A quad junction common anode design in a SC-74 package protects four separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. A simplified example of MMQA/SZMMQA Series Device applications is illustrated below.

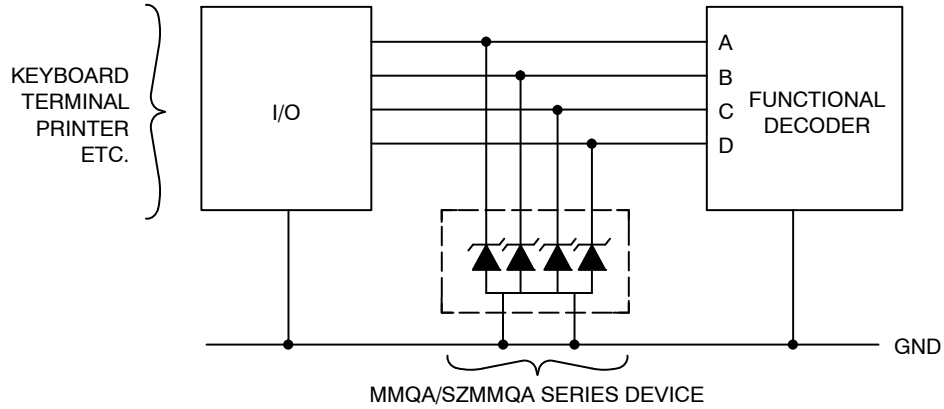


Figure 9. Computer Interface Protection

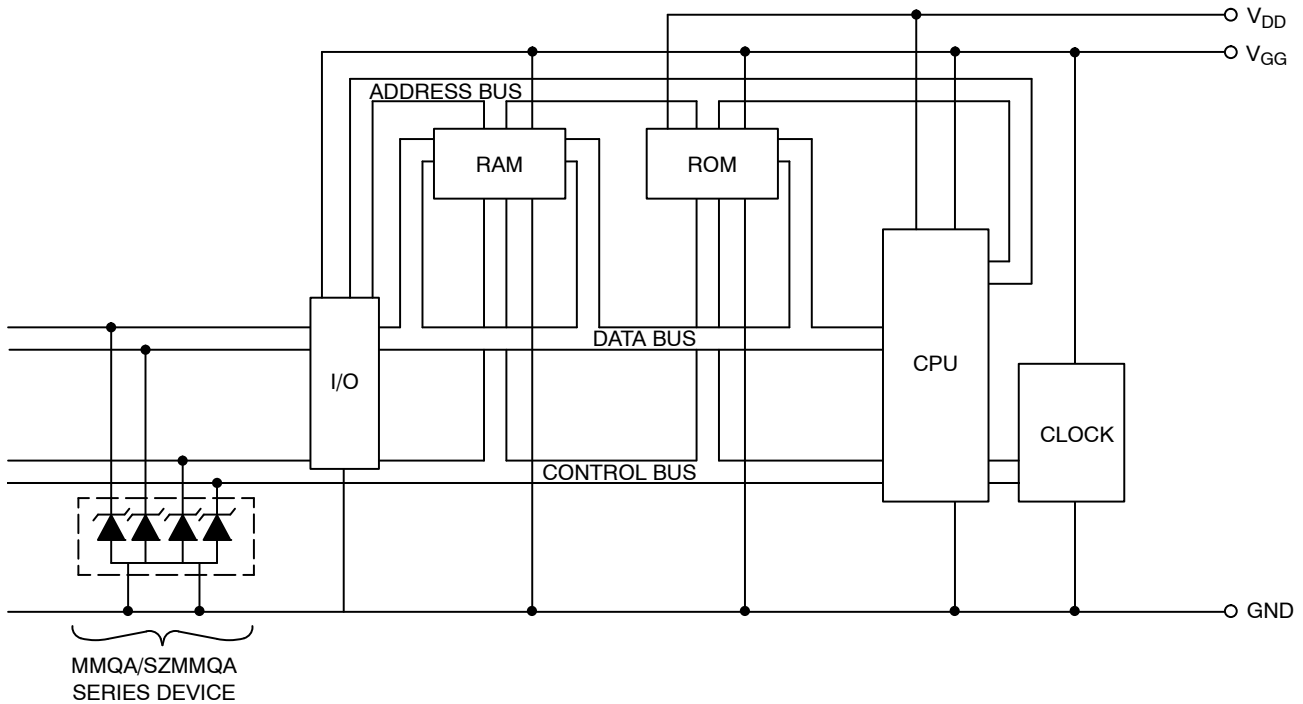


Figure 10. Microprocessor Protection

MMQA, SZMMQA Quad Common Anode Series

DEVICE MARKING AND ORDERING INFORMATION

Device*	Device Marking	Package	Shipping
MMQA5V6T1	5A6	SC-74	3,000/Tape & Reel
MMQA6V2T1	6A2	SC-74	3,000/Tape & Reel
MMQA6V2T3	6A2	SC-74	10,000/Tape & Reel
MMQA6V8T1	6A8	SC-74	3,000/Tape & Reel
MMQA12VT1	12A	SC-74	3,000/Tape & Reel
MMQA13VT1	13A	SC-74	3,000/Tape & Reel
MMQA15VT1	15A	SC-74	3,000/Tape & Reel
MMQA18VT1	18A	SC-74	3,000/Tape & Reel
MMQA20VT1	20A	SC-74	3,000/Tape & Reel
MMQA20VT3	20A	SC-74	10,000/Tape & Reel
MMQA21VT1	21A	SC-74	3,000/Tape & Reel
MMQA22VT1	22A	SC-74	3,000/Tape & Reel
MMQA24VT1	24A	SC-74	3,000/Tape & Reel
MMQA27VT1	27A	SC-74	3,000/Tape & Reel
MMQA27VT3	27A	SC-74	10,000/Tape & Reel
MMQA33VT1	33A	SC-74	3,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*Include SZ-prefix devices where applicable.

Mechanical Characteristics:

CASE: Void-free, Transfer-molded, Thermosetting Plastic Case.

FINISH: Corrosion resistant finish, easily solderable.

Package designed for optimal automated board assembly.

Small package size for high density applications.

Available in 8 mm Tape and Reel.

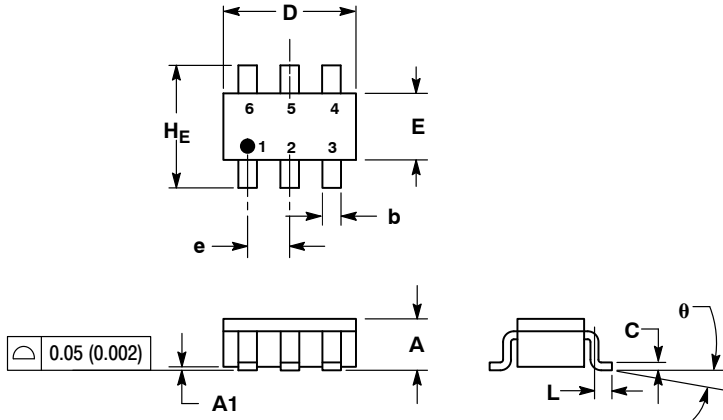
Use the Device Number to order the 7 inch/3,000 unit reel.

Replace the "T1" with "T3" in the Device Number to order the 13 inch/10,000 unit reel.

MMQA, SZMMQA Quad Common Anode Series

PACKAGE DIMENSIONS

SC-74
CASE 318F-05
ISSUE M

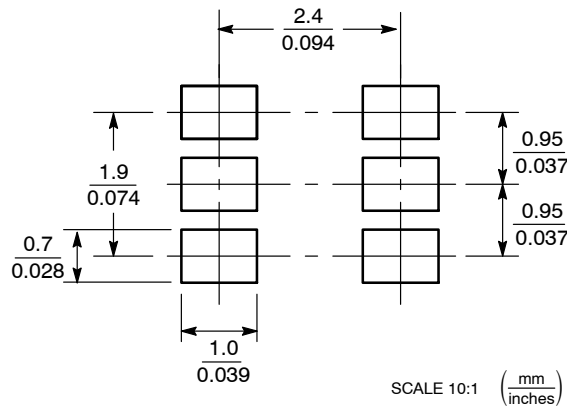


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
θ	0°	-	10°	0°	-	10°

- STYLE 1:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local Sales Representative



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.